



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Abbott, et al.

Serial No.: 09/514,762 ✓

Filed: 02/28/00

For: Double Sided Flexible Circuit for Integrated Circuit Packages and Method  
of Manufacture

Docket No.: TI-26904

Examiner: Chang, R. K.

Art Unit: 3729

AF/3729  
#18 / DE election

Provisional Election with Traverse gw dny/108103

Assistant Commissioner of Patents  
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with the  
U.S. Postal Service as First Class Mail in an envelope addressed to:

Assistant Commissioner for Patents, Washington, D.C. 20231 on

March 25, 2003

Elizabeth Austin

Dear Sir:

The following amendments and remarks are offered in response to the  
Examiner's Office Action dated 02/25/2003. They are respectfully submitted as a  
full and complete response to that Action.

The Examiner has restricted prosecution in this application to one of the  
allegedly distinct species of the claimed invention:

- I. Claim 16.
- II. Claim 18.
- III. Claims 21-25.

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### Provisional Election

Applicants provisionally elect to prosecute the claims of Group III, Claims 21-25. However, as indicated below, Applicant is of the opinion that Group II, Claim 18 should be prosecuted along with Claims 21-25, as Claim 21 is generic to Claim 18.

### Traversal of Restriction Requirement

The restriction requirement is based on the Examiner's assertion that no generic claim currently exists. Applicant traverses the requirement. Claim 21 is generic to the invention described in Claim 18. For example, the step of "positioning adjacent to said film an embossing tool having raised areas comprising a pattern of conductors and vias corresponding to a circuit design, wherein said raised areas are coated with a thin layer of metal" is clearly generic to the step in Claim 18 of "superimposing on said film an embossing tool having raised areas comprising a pattern of conductors and vias corresponding to a circuit design, wherein, said raised areas are coated with a thin layer of metal, comprising copper." Similarly, the step in Claim 21 of "applying heat and pressure on said tool to simultaneously emboss the film and to transfer said thin metal layer from the embossing tool to the polymer film" is clearly generic to the step in Claim 18 of "applying heat and pressure to simultaneously emboss the film and to transfer said thin metal layer from the embossing tool to the polymer film." Likewise, the step in Claim 21 of "plating a second layer of metal on said transferred thin metal layer" is generic to the step in Claim 18 of "plating a layer of copper to fill the vias and conductor patterns on both sides of the film." Therefore, Applicant respectfully requests that the Examiner reconsider the restriction requirement and maintain pendency in the application of at least Claims 18 and 21-25.

The Examiner has asserted that the amendment filed by Applicant on 1/10/03 was deficient in that it lacked a marked-up version of the amended

claims. Applicant respectfully disagrees. A copy of the amendment is included herewith, and it clearly includes a marked up version of amended Claims 16 and 18.

The amended abstract presented in the amendment filed by Applicant on 1/10/03 was objected to as not being presented on a separate sheet. A copy of the amended abstract on a separate sheet is being provided herewith.

If the Examiner has any questions or other correspondence regarding this application, Applicant requests that the Examiner contact Applicant's attorney at the below listed telephone number and address.

Texas Instruments Incorporated  
P.O. Box 655474, M/S 3999  
Dallas, TX 75265  
Phone: 972 917-5653  
Fax: 972 917-4418

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'M. Skrehot', followed by a long horizontal flourish.

Michael K. Skrehot  
Reg. No. 36,682



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Abbott, et al.

Serial No.: 09/514,762

Filed: 02/28/00

For: Double Sided Flexible Circuit for Integrated Circuit Packages and Method of  
Manufacture

Docket No.: TI-26709

Examiner: Chang, R. K.

Art Unit: 3729

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Amendment under 37 CFR 1.116

Assistant Commissioner of Patents  
Washington, DC 20231

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

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U.S. Postal Service as First Class Mail in an envelope addressed to:  
Assistant Commissioner for Patents, Washington, D.C. 20231 on

*Jan. 10, 2003*

Elizabeth Austin

The following amendments and remarks are offered in response to the Examiner's Office Action dated 09/11/02. They are respectfully submitted as a full and complete response to that Action. A petition for a one month extension under 37 CFR 1.136(a) accompanies this response. Any further necessary extension of time is hereby requested. The Commissioner is authorized and is hereby requested to charges any and all fees to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

Please amend the above-referenced application as follows:

In the Specification, please delete the Abstract and insert the following: